WHAT IS CLAIMED IS:

1. A heat reflecting device for a semiconductor processing apparatus comprising a process chamber, wherein the heat reflecting device comprises at least one heat reflecting unit, each of which has a reflecting surface capable of reflecting heat, and the heat reflecting device is disposed in the periphery of the process chamber;

the heat reflecting device further comprising a position shifting unit which is connected with the at least one heat reflecting unit to drive the heat reflecting unit to move, so that during the temperature-rising or temperature-maintaining period for the process chamber, the reflecting surface of the at least one heat reflecting unit can be made to face towards the process chamber to reflect heat to it; and during the temperature-falling period for the process chamber, the reflecting surface of the at least one heat reflecting unit can be made to deviate from the process chamber for facilitating heat dissipation of the process chamber.

~~2. The heat reflecting device of claim 1, further comprising a position shifting unit which is connected with the at least one heat reflecting unit to drive the heat reflecting unit to move, so that during the temperature-rising or temperature-maintaining period for the process chamber, the reflecting surface of the at least one heat reflecting unit can be made to face towards the process chamber to reflect heat to it; and during the temperature-falling period for the process chamber, the reflecting surface of the at least one heat reflecting unit can be made to deviate from the process chamber for facilitating heat dissipation of the process chamber.~~

~~3~~2. The heat reflecting device of claim ~~2~~1, wherein the position shifting unit comprises an elevating device which makes the reflecting surface of the at least one heat reflecting unit face towards or deviate from the process chamber by driving the heat reflecting unit to move vertically.

43. The heat reflecting device of claim 21, wherein the number of the at least one heat reflecting unit is at least two, and the position shifting unit comprises a rotating device for driving the heat reflecting device to rotate by an angle so that the reflecting surfaces of the heat reflecting units face towards or deviate from the process chamber.

54. The heat reflecting device of claim 43, wherein the number of the heat reflecting units is at least 2n, and n pivot shafts for installing the heat reflecting units are provided in the rotating device, wherein n is an integer not less than 1;

for each pivot shaft, two heat reflecting units closely adjacent to the pivot shaft at both sides are provided on the pivot shaft and can rotate around it, so that the reflecting surfaces of the heat reflecting units face towards or deviate from the process chamber according to process requirements.

65. The heat reflecting device of claim 43, wherein the number of the heat reflecting units is m, and m pivot shafts for installing the heat reflecting units are provided in the rotating device, wherein m is an integer not less than 2;

the m heat reflecting units correspond to the m pivot shafts one to one, each heat reflecting unit is fixed to a pivot shaft corresponding thereto to rotate with it, or each heat reflecting unit is provided to a pivot shaft corresponding thereto to rotate around it, so that the reflecting surface of the heating reflecting unit is made to face towards or deviate from the process chamber according to process requirements.

76. The heat reflecting device of any one of claims 1-65, wherein during the temperature-rising or temperature-maintaining period for the process chamber, the reflecting surface of the heat reflecting unit extends along the direction of the tangent line to the process chamber; during the temperature-falling period for the process chamber, the reflecting surface of the heating reflecting unit extends along the direction of the normal line to the process chamber.

~~8~~7. The heat reflecting device of claim ~~5~~4 or ~~6~~5, wherein the rotating device comprises at least one rotation-driving source, each heat reflecting unit is connected to the rotation-driving source and is driven by the rotation-driving source to rotate.

~~9~~8. The heat reflecting device of claim ~~8~~7, wherein in the rotating device, corresponding to each heat reflecting unit, a rotation delivering part is provided, the rotation delivering part is connected between the rotation-driving source and the heat reflecting unit, and delivers rotation driving force from the rotation-driving source to the heat reflecting unit.

~~10~~9. The heat reflecting device of claim ~~9~~8, wherein there is one rotation-driving source provided, each rotation delivering part is connected to said one rotation-driving source to deliver the rotation driving force from the rotating driving source to each heat reflecting unit.

~~11~~10. The heat reflecting device of claim 1, wherein the tolerance temperature of the heat reflecting unit is 1500 ℃, and each heat reflecting unit comprises k heat-radiation reflecting mirrors which are arranged with certain intervals, wherein, k is an integer not less than 2.

~~12~~11. The heat reflecting device of claim ~~11~~10, wherein the heat-radiation reflecting mirror is made of copper plate, aluminum plate, steel plate or silver plate.

~~13~~12. The heat reflecting device of claim ~~11~~10, wherein the heat-radiation reflecting mirror consists of a base and a reflecting film on the surface of the base.

~~14~~13. The heat reflecting device of claim ~~13~~12, wherein the base of the heat-radiation reflecting mirror comprises a copper plate, an aluminum plate, a steel plate or a silver plate, and the reflecting film is metal plating or metal coating.

~~15~~14. A semiconductor processing apparatus comprising a process chamber, wherein a heat reflecting device of any one of claims 1-~~14~~13 is disposed in the periphery of the process chamber.

~~16~~15. The semiconductor processing apparatus of claim ~~15~~14, wherein an induction heater is provided outside the process chamber for heating the process chamber, and the heat reflecting device is provided in the periphery of the induction heater to reflect heat towards the process chamber.

~~17~~16. The semiconductor processing apparatus of claim ~~16~~15 wherein a tray device for carrying substrates to be processed is provided in the process chamber.

~~18~~17. The semiconductor processing apparatus of claim ~~17~~16, wherein the semiconductor processing apparatus includes a crystallized film growth apparatus, the tray device comprises a plurality of trays stacked together, and there is a distance between two adjacent trays.

~~19~~18. The semiconductor processing apparatus of claim ~~18~~17, wherein said plurality of trays are stacked together longitudinally along the height direction of the process chamber.